

High Surge Current Series - DO-214



Agency Approvals

Agency	Agency File Number
	E133083

Pinout Designation

Not Applicable

Schematic Symbol



Description

The High Surge Current DO-214 Series are SIDACtor® thyristors designed to protect equipment located in hostile environments from overvoltage transients.

The series provides a 200A 10/1000 μ s rated surface mount solution that enables equipment to comply with enhanced surge requirements now specified in regulatory and customer requirements.

Features and Benefits

- Low voltage overshoot
 - Low on-state voltage
 - Does not degrade surge capability after multiple surge events within limit.
 - Fails short circuit when surged in excess of ratings
 - 200A 10x1000 Surge
- Rating
- 1000A 2x10 Surge Rating
 - RoHS Compliant and Halogen-Free
 - Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

Applicable Global Standards

- TIA-968-A
- TIA-968-B
- ITU K.20/21/45 Enhanced Level
- ITU K.20/21/45 Basic Level
- GR 1089 Intra-building
- IEC 61000-4-5 2nd edition
- YD/T 1082
- YD/T 993
- YD/T 950
- GR 1089 Inter-building

Electrical Characteristics

Part Number	Marking	V_{DRM} @ $I_{DRM}=5\mu A$	V_s @ 100V/ μ s	I_H	I_s	I_{T++}	V_T @ $I_T=2.2A$	Capacitance @ 1MHz, 2V bias	
		V min	V max	mA min	mA max	A max	V max	pf min	pF max
P0080SDLRP	P-8D	6	25	50	800	2.2	4	50	150
P0640SDLRP	P06D	58	77	50	800	2.2	4	100	160
P0720SDLRP	P07D	65	88	50	800	2.2	4	100	150
P0900SDLRP	P09D	75	98	50	800	2.2	4	95	140
P1100SDLRP	P11D	90	130	50	800	2.2	4	75	115
P1300SDLRP	P13D	120	160	50	800	2.2	4	65	100
P1500SDLRP	P15D	140	180	50	800	2.2	4	60	90
P1800SDLRP	P18D	170	220	50	800	2.2	4	50	90
P2300SDLRP	P23D	190	260	50	800	2.2	4	50	80
P2600SDLRP	P26D	220	300	50	800	2.2	4	50	75
P3100SDLRP	P31D	275	350	50	800	2.2	4	45	70
P3500SDLRP	P35D	320	400	50	800	2.2	4	45	65

Notes:

- Absolute maximum ratings measured at $T_a = 25^\circ C$ (unless otherwise noted).

- Components are bi-directional (unless otherwise noted).

** Will meet 4.4A power cross requirement without fire hazard.

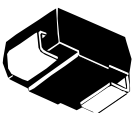
Surge Ratings

Series	I_{PP}									I_{TSM} 50/60 Hz	di/dt
	0.2/310 ¹	2/10 ¹	8/20 ¹	10/160 ¹	10/560 ¹	5/320 ¹	10/360 ¹	10/1000 ¹	5/310 ¹		
	0.5/700 ²	2/10 ²	1.2/50 ²	10/160 ²	10/560 ²	9/720 ²	10/360 ²	10/1000 ²	10/700 ²		
	A min	A min	A min	A min	A min	A min	A min	A min	A min	A min	A/μs max
D	—	1000	800	—	—	—	—	200	350	50	1000

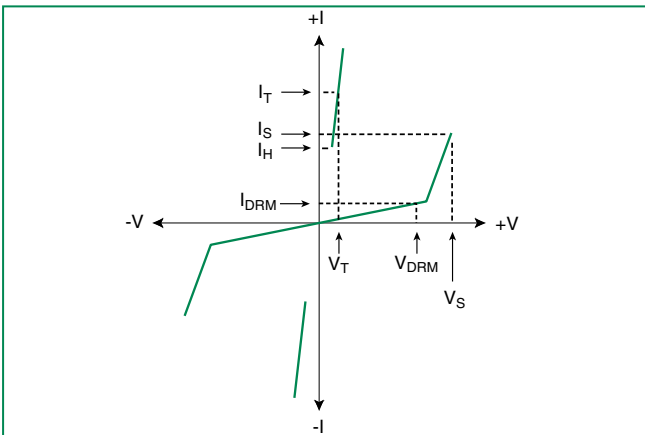
Notes:

- 1 Current waveform in μs
- 2 Voltage waveform in μs
- Peak pulse current rating (I_{pp}) is repetitive and guaranteed for the life of the product that remains in thermal equilibrium.
- I_{pp} ratings applicable over temperature range of -40°C to +85°C
- The component must initially be in thermal equilibrium with -40°C ≤ T_J ≤ +150°C

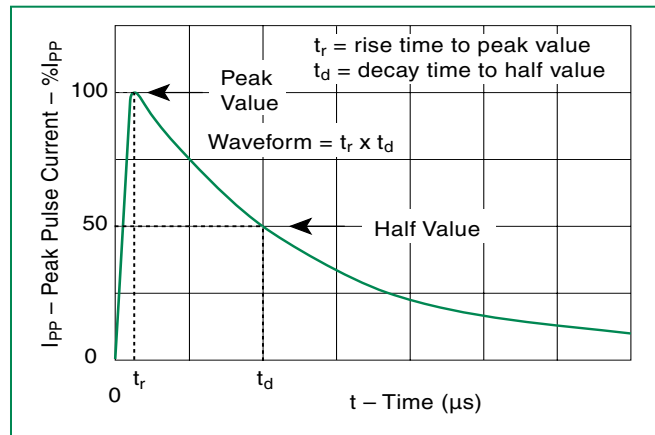
Thermal Considerations

Package	Symbol	Parameter	Value	Unit
DO-214AA 	T_J	Operating Junction Temperature Range	-40 to +150	°C
	T_S	Storage Temperature Range	-65 to +150	°C
	$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	90	°C/W

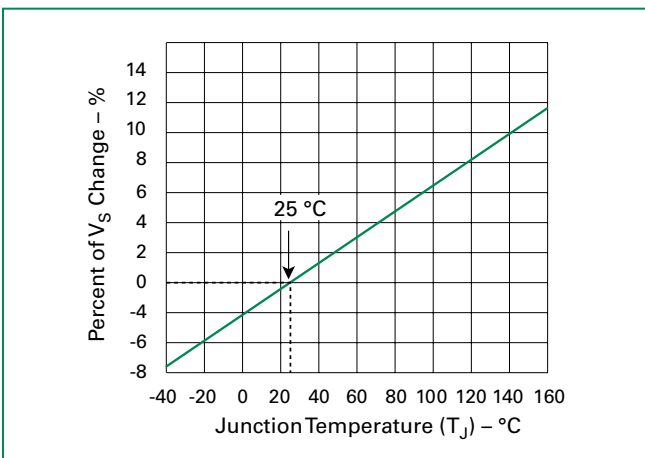
V-I Characteristics



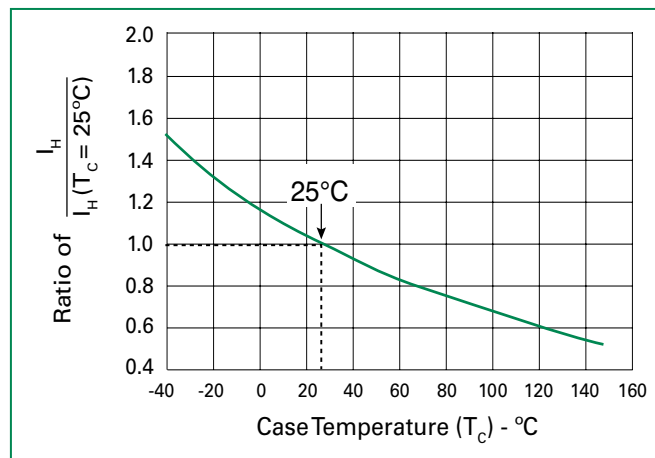
$t_r \times t_d$ Pulse Waveform



Normalized V_S Change vs. Junction Temperature

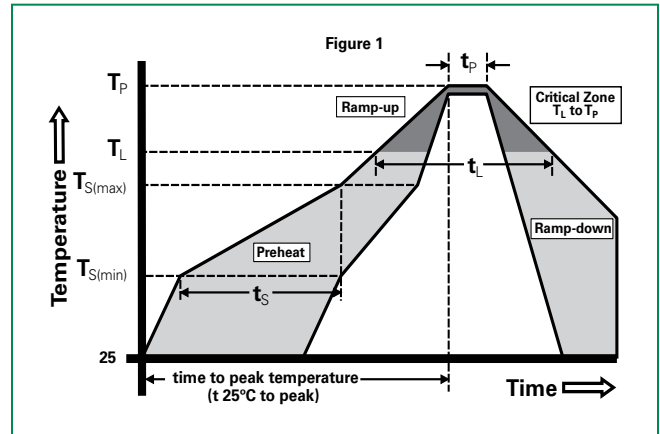


Normalized DC Holding Current vs. Case Temperature



Soldering Parameters

Reflow Condition	Pb-Free assembly (see Fig. 1)	
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max ($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L) to peak)	3°C/sec. Max.	
$T_{s(max)}$ to T_L - Ramp-up Rate	3°C/sec. Max.	
Reflow	-Temperature (T_L) (Liquidus)	+217°C
	-Temperature (t_L)	60-150 secs.
Peak Temp (T_p)	+260(+0/-5)°C	
Time within 5°C of actual PeakTemp (t_p)	30 secs. Max.	
Ramp-down Rate	6°C/sec. Max.	
Time 25°C to Peak Temp (T_p)	8 min. Max.	
Do not exceed	+260°C	



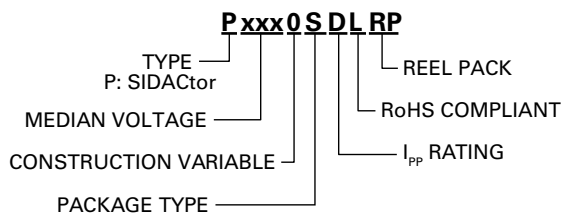
Physical Specifications

Lead Material	Copper Alloy
Terminal Finish	100% Matte-Tin Plated
Body Material	UL Recognized epoxy meeting flammability classification V-0 per Underwriters Laboratories

Environmental Specifications

High Temp Voltage Blocking	80% Rated V_{DRM} ($V_{AC Peak}$) +125°C or +150°C, 504 or 1008 hrs. MIL-STD-750 (Method 1040) JEDEC, JESD22-A-101
Temp Cycling	-65°C to +150°C, 15 min. dwell, 10 up to 100 cycles. MIL-STD-750 (Method 1051) EIA/JEDEC, JESD22-A-104
Biased Temp & Humidity	52 V_{DC} (+85°C) 85%RH, 504 up to 1008 hrs. EIA/JEDEC, JESD22-A-101
High Temp Storage	+150°C 1008 hrs. MIL-STD-750 (Method 1031) JEDEC, JESD22-A-101
Low Temp Storage	-65°C, 1008 hrs.
Thermal Shock	0°C to +100°C, 5 min. dwell, 10 sec. transfer, 10 cycles. MIL-STD-750 (Method 1056) JEDEC, JESD22-A-106
Autoclave (Pressure Cooker Test)	+121°C, 100%RH, 2atm, 24 up to 168 hrs. EIA/JEDEC, JESD22-A-102
Resistance to Solder Heat	+260°C, 30 secs. MIL-STD-750 (Method 2031)
Moisture Sensitivity Level	85%RH, +85°C, 168 hrs., 3 reflow cycles (+260°C Peak). JEDEC-J-STD-020, Level 1

Part Numbering



Part Marking

